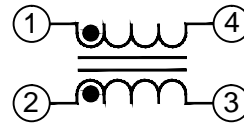
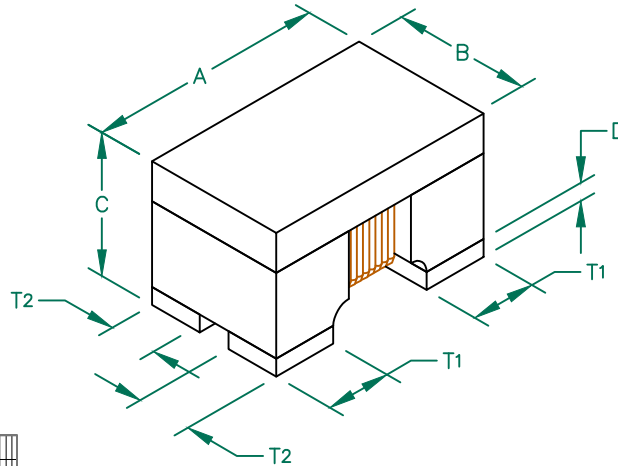


CM0805D900R-10

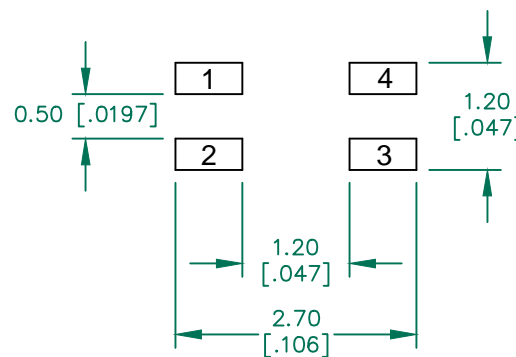
PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.20 [.047]	+ 0.20 [.008]
C	1.20 [.047]	+ 0.20 [.008]
D	0.15 [.006]	+ 0.10 [.004]

T1	0.55 [.022]	+ 0.10 [.004]
T2	0.46 [.018]	+ 0.10 [.004]



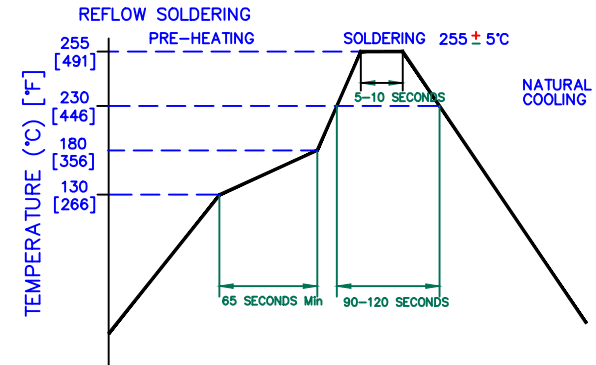
LAND PATTERNS FOR REFLOW SOLDERING



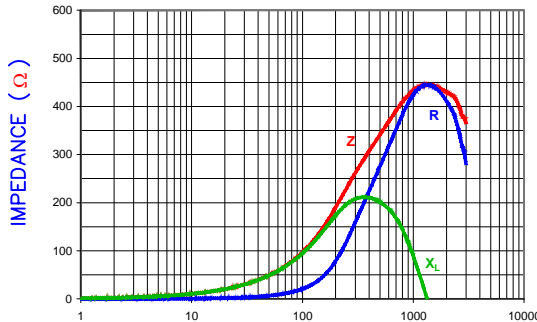
Electrical Characteristics		Nominal	Min	Max
Common Mode Impedance @ 100MHz	(Ω)	90	67.5	112.5
DCR	(Ω)	-	-	0.3
Rated Current	(mA)	-	-	400

- NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, EMBOSSED PLASTIC TAPE 2,000 PCS/REEL.
 2. TERMINATION FINISH 100% MATTE TIN.
 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
 4. OPERATING TEMP. RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS

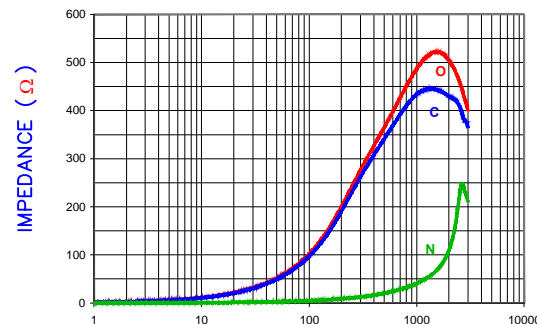


Z, R, XL vs. FREQUENCY



FREQUENCY (MHz)

Z vs. FREQUENCY (C,N,O)



FREQUENCY (MHz)

Open Common Normal



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	Laird PROJECT/PART NUMBER: CM0805D900R-10 DATE: 08/11/06 SCALE: NTS SHEET: 1 of 1			
D	UPDATE SOLDERING TEMPERATURE	04/01/11	WEI				
C	UPDATE COMPANY LOGO	04/28/09	JRK				
B	UPDATE COMPANY LOGO	05/14/07	JRK				
A	ORIGINAL DRAFT	08/11/06	JRK				
REV	DESCRIPTION	DATE	INT				